Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Previously presented) An electronic package, comprising:

a conductive trace layer having a first side and a second side, the conductive trace layer being patterned to define a plurality of interconnect pads;

a dielectric substrate mounted on the first side of the conductive trace layer;

an embedded capacitor having a capacitance of from about 1 nF/sq.cm. to about 100 nF/sq.cm., including a first conductive layer, a second conductive layer and a layer of dielectric material made of a non-conductive polymer blended with high dielectric constant particles disposed between the first and the second conductive layers, the first conductive layer attached to the second side of the conductive trace layer by a first adhesive layer;

a plurality of interconnect regions extending through the first conductive layer and the dielectric material layer of the capacitor; and

an interconnect member connected between each of the conductive layers of the capacitor and a corresponding set of the interconnect pads, the first conductive layer of the capacitor being electrically connected to a first set of the interconnect pads and the second conductive layer of the capacitor being electrically connected to a second set of the interconnect pads, the interconnect members corresponding to the second set of interconnect pads extending through one of the interconnect regions.

2. (Original) The electronic package of claim 1 wherein the first electrode is maintained at a first reference voltage and wherein the second electrode is maintained at a second reference voltage different from the first reference voltage.

3. (Previously presented) The electronic package of claim 1 further comprising an electrically conductive stiffening member attached to the second conductive layer of the capacitor by a second adhesive layer.

4. (Previously presented) The electronic package of claim 3 further comprising a device receiving region extending through the dielectric substrate, the conductive trace layer and the capacitor, and further comprising an electronic device attached to the device receiving region on the stiffening member by a third adhesive layer.

5. (Cancelled)

6. (Cancelled)

7. (Cancelled)

8. (Original) The electronic package of claim 1 wherein the capacitor has a capacitance of from about 2 nF/sq. cm. to about 30 nF/sq. cm.

9. (Original) The electronic package of claim 1 wherein the capacitor has a capacitance of from about 5 nF/sq. cm. to about 15 nF/sq. cm.

10. (Original) The electronic package of claim 1 wherein the capacitor has a capacitance of at least 30nF/sq. cm.

11. (Previously presented) The electronic package of claim 1 wherein the dielectric material of the capacitor has a thickness of from about 0.5 um to about 30 um.

12. (Original) The electronic package of claim 1 wherein the dielectric material of the capacitor includes a metal oxide.

13. (Previously presented) The electronic package of claim 1 wherein the dielectric constant particles are formed from a material selected from the group consisting of barium titanate, barium strontium titanate, titanium oxide, lead zirconium titanate and tantalum oxide.

14. (Original) The electronic package of claim 1 wherein the dielectric substrate includes a plurality of apertures, each one of the apertures being positioned adjacent to one of the interconnect region of the capacitor.

15. (Original) The electronic package of claim 1 wherein the dielectric substrate includes a polymeric film.

16. (Original) The electronic package of claim 15 wherein said polymeric film is polyimide film.

17. (Original) The electronic package of claim 1 wherein the interconnect member is a solder plug.

18. (Original) The electronic package of claim 1 wherein each interconnect pad is a solderball pad.

19. (Previously presented) The electronic package of claim 18 wherein the dielectric substrate has an aperture extending therethrough adjacent to each solderball pad.

20. (Cancelled)

21. (Cancelled).

22. (Cancelled)

23. (Cancelled)

24. (Cancelled)

25. (Cancelled)

26. (Cancelled)